



Date :	15-Oct-25	Factory :	122T03
HT color :	L1-Light Raspberry 147-82-14	Fabric No :	TEI80032-6MFX2
Reference No :	NBFK24080235	Fabric color :	PINK HEAT-COLORO-148-62-42
Quality :	SAM	Application Side :	FACE
Glue :	EK		
HT Description :	(SAM-EK)NB26-BE-FNB2.5-SAM_Flying NB 2.5in		

**CONCLUSION :****COMMENTS :**

1.Adherence &amp; Surface Appearance after wash-40°C\*10cycles M

2.Elasticity Test M

3.Dye Migration M

4.CF to Rubbing M

M = Meet buyer's requirement

F = Below buyer's requirement

N/A = Not applicable

\* = No specified requirement or fair

**1.After Wash**

-Washing Temperature(°C) :	40
-Washing Cycle :	10
-Drying :	LOW
-Drying Cycle :	10

	GRADING	REQUIREMENT
-Adherence :	5.0	4.0
-Surface Appearance :	5.0	4.0
-Color Change :	5.0	3.5
-Color Staining :	4.0	3.5

**2.Elasticity Test**

	RESULT	REQUIREMENT
-Before wash :	ACCEPTED	No Cracking
-After wash :	ACCEPTED	No Cracking

**3.Dye Migration**

-Temperature(°C) :	70
-Operation Time(hr) :	48

	GRADING	REQUIREMENT
-Color Change :	5.0	4.0
-Self Staining :	4.5	4.5

**4.CF to Rubbing**

	GRADING	REQUIREMENT
-Color Staining(DRY) :	4.5	4.0
-Color Staining(WET) :	4.5	3.0

**OVERALL COMMENTS FROM LAB :**

After pressing, the appearance of the other side of the fabric has changed from the original.



## OPERATING INSTRUCTIONS

蓋墊縮回

Report No. : TL11410075-1-1-F Application surface : FACE  
 HT No. : NBFK24080235 Code : SAM-EK  
 Item : (SAM-EK)NB26-BE-FNB2.5-SAM\_Flying NB 2.5in  
 Effect : 超強抗昇華效果 (Super Anti-Migration)/高彈性針織布膠(Beyond Elastic Series)  
 Fabric no : TEI80032-6MFX2

## Real touch Heat transfer condition: 實際接觸轉印標壓燙條件

## &lt;1st-step application&gt;

♦Cover with a Teflon, white paper, or release paper on the top to reduce the static electricity. 壓燙時，需覆蓋白紙/鐵氟龍/離型紙以降低靜電。  
 ♦Please pre-heat fabrication 10 secs with below suggested 1st step temp. and pressure condition. 請依第一步驟的壓燙溫度及壓力，預先縮布10秒。  
 ♦Pls follow the suggested peeling time show on heat transfer package after 1st heat press, and followed by 2nd heat apply ASAP. 第1段壓燙後請依照撕紙時間撕紙，勿久置。並盡速完成第2段壓燙。

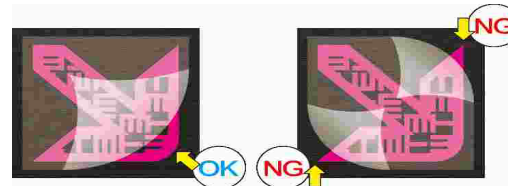
Temperature :	150 °C	302 °F
Pressure :	40 Psi	2.8 Kg/cm <sup>2</sup>
Apply Pressure	Use fabric mat 使用墊布	
Time :	15 sec	

Peeling Time : Peeling time is instructed by heat transfer package.  
 Cold Peel: wait 2-5 min  
 Warm-Cold Peel: wait 20-60 sec  
 Warm Peel: wait 10-30 sec  
 Hot Peel: wait 5-10 sec

## &lt;2nd-step application&gt;

♦Cover with a teflon or release paper on the top to prevent the glue from adhering to the plate. 壓燙時，需覆蓋離型紙/鐵氟龍以避免汙染壓燙台。  
 ♦Reapply on the face side of heat transfer to enhance the durability. 正面回壓：增加轉印標牢度。

Temperature :	150 °C	302 °F
Pressure :	40 Psi	2.8 Kg/cm <sup>2</sup>
Apply Pressure		
Time :	5 sec	



When peel off the release paper (PET), please peel from arc part of graphic instead of sharp angle to prevent the damage of heat transfer. 撕紙時須從圖形結構為圓弧處撕起，避免從尖角處容易造成損壞。

After pressing the heat transfer, please do not throw the cloth as the glue is not yet completely cooling. 壓燙後，因膠未完全冷卻，請勿甩布。

In-house Heat Transfer Application Machinery Model: Hotronix Air Fusion(Platen 16""X20"" , Air Cylinder 6"" ). Please ensure the application temperature within 2.5°C (5°F) range of suggested temperature. 依田使用的壓燙機型號為Platen 16""X20"" , Air Cylinder 6"" , 請確保壓台溫差可保持在建議壓燙溫度2.5°C(5°F)以內"

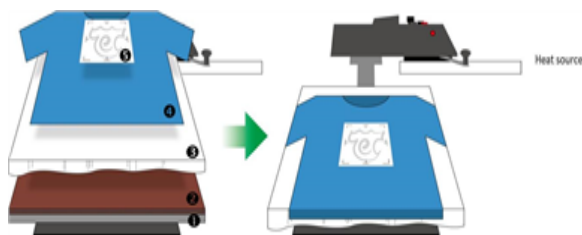
Please review the test specimen by following brand's test manual, and avoid using hard, sharp object such as finger nail to damage the HT. 請依照品牌測試標準文來檢視測試樣，避免使用尖銳硬物像是指甲來破壞轉印標表面

Due to the variety of fabric composition and structure, please follow above suggested conditions to ensure the glue can be completely melted to present the best appearance and quality. 因布的組織與結構多元，為確保膠能充分熱熔，以呈現最好的外觀品質與牢度，請依照指示操作。

Suggestion: Use "fabric-mat" with the thickness of 3mm~4mm to provide a buffer and even pressure to ensure the application durability. 使用3mm~4mm厚度的布墊來平均壓力以確保牢度

Fabric with mesh hole or with obvious texture requires this application method. 網紗布或紋路起伏較大的布種，建議使用此壓燙方式。

## Application Graphic :



Layer ①: Heat-pressing machine platen  
 Layer ②: A full page of silicon pad (10MM)  
 Layer ③: Fabric-Mat  
 Layer ④: Panel  
 Layer ⑤: HT

\* Please see the back page for important remark 請參照背面注意事項說明 \*